

Prototyping boards

3 Plane high density DIP board

Ideal for high density circuitry using wirewrapping, hardwiring or Verowire interconnection techniques. The board features two power rail options, either as two 0V or one Vcc and a ground plane on the component side. Power rails run between rows of 7,62 pitch integrated circuits allowing end-to-end stacking for increased packing density.

Features

- High packing density
- Two Vcc and one 0V power rail options
- DIN 41494 cardframe compatible
- DIN 41612 connector pattern, up to 64/96 ways
- Microbus backplane compatible

Backplane compatible

By utilising a simple track break facility to isolate Vcc from pin 32, high density DIP boards are fully compatible with the Vero Technologies Microbus backplane range.

3 Plane high density DIP board			Ordering information
Board dimensions	7,61 pitch IC DIP rows/pads	15,24 pitch IC DIP rows/pads	Order code
100 x 160	5/53	4/53	10-0581

Notes: hole grid 2,54 x 2,54mm Hole dia. 1,02mm; 3,81mm gap on double height boards

DIN 41494 Compatible DIP Board

A low density board designed for hard wiring of integrated circuits. 0V and Vcc rail patterns are duplicated on the component side of the board giving increased power distribution. Connector pattern at rear edge of board allows input/output via ribbon cable headers.

Features

- DIN 41494 cardframe compatible
- DIN 41612 connector position, up to 64/96 ways
- Rear end input/output facility
- Microbus backplane compatible, with a grid print to aid component layout
- Ample room for wiring looms and/or discrete components

Note: The board pattern is turned through 90° on double height Eurocard versions in order to maximise packing density.

DIN 41494 Compatible DIP Board				Ordering information
Board dimensions	7,62 pitch IC DIP rows/pads	15,24 pitch IC DIP rows/pads	Base material	Order code
100 x 160	4/32	3/32	Epoxy	10-2446

Note: hole grid 2,54 x 2,54mm Hole dia. 1,02mm

DIN 41494 Eurocard: Veroboard Pattern

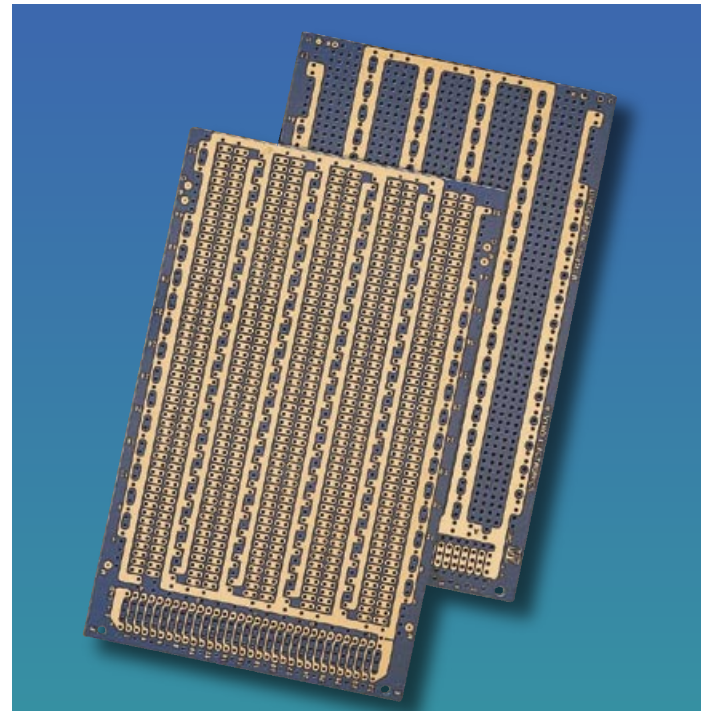
A unique board giving the advantages of Veroboard with the flexibility of Eurocard and DIN 41612 connectors. Primarily used for hard wiring of discrete components, typically in analogue circuits, it is equally useful where a number of common bus or signal lines are required. For wirewrapping applications a 3,81mm gap on the double height boards maintains board patterns on grid with adjacent connectors.

Features

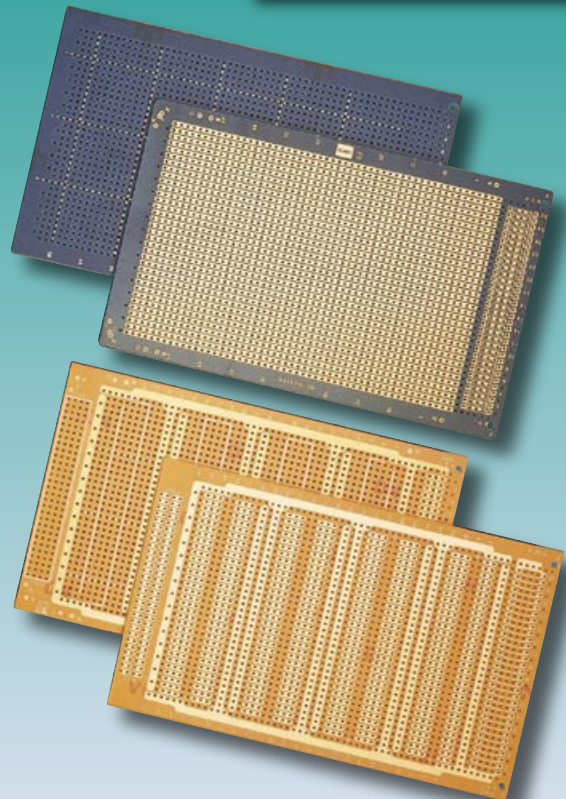
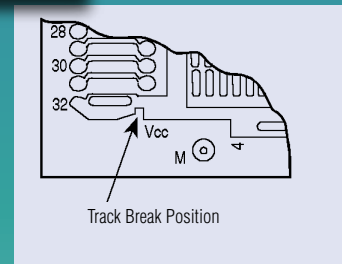
- DIN 41494 cardframe compatible
- Ideal for hard wiring of discrete components; grid pattern to aid component layout
- Microbus backplane compatible, and available in Eurocard sizes

DIN 41494 Eurocard, Veroboard Pattern				Ordering information
Board dimensions	Tracks	Holes per track	Base material	Order code
100 x 160	34	52	Epoxy	10-2449
100 x 220	34	77	Epoxy	10-27558

Notes: Hole grid 2,54 x 2,54mm Hole dia. 1,02mm; 3,81mm gap on double height versions



3 Plane High-density DIP board



DIN 41494 Compatible DIP Board and Veroboard pattern Eurocard